© Copyrig	l Composition De ht 2005. IPC, Bannock al and Pan-American c	burn, Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration e	on of the su	bstances v s all lower	vithin the manufactur level materials for w	rer listed ite hich the ma	m. Note: i nufacturer	f the item is an as r has engineering	sembly with low responsibility.
	-21.1 IPC Web Site for Information on IPC-1752 Standard Form Type Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
upplier Information													
ompany name*		Company uni	que ID		1	Unique ID Auth	ority			Response	Date*		
nsemi										2025-07-1	5		
ontact Name		Title - Contac	et		]	Phone - Contac	t*	Email - Contact*					
Product-Env-Stewards		Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* T			presentative Phone - Representative* Email - Representative*				ative*						
roduct-Env-Stewards		Product Envi	ro Compliance	npliance NA Product-Env-Stewards@onsemi				ards@onsemi.co	m				
Requester Item Numb	er Mfr Iter	n Number	Mfr Item Name			Effective Date	Version	М	lanufacturing Site	W	'eight*	UOM	Unit Type
	AR0132 A0-AA	AT6G00XPE DRBR	1MP 1/3 CIS SO			2025-07-15		Т	WU	19	98.94	mg	Each
Ianufacturing Proccess I	nformation												
Terminal Plating / Grid	Array Material	Terminal Base A	Alloy	J-STD-020 MSL	Rating	Peak Proc	ess Body To	emperature	Max Time at Peak	Temperatu	re Numb	per of Reflow Cyc	les
SnAgCu		CU Alloy		3		260		С	30	second	s 3		
omments													
TTENTION: MSL 3 Rated iter	n requires Bake and l	Dry Pack (after	electrical test)										
or more information regarding	material composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth						
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	46.746	mg		Misc.	proprietary data		0.1776	mg
			Supplier	Silicon (Si)	7440-21-3		46.1056	mg
			Supplier	Aluminum (Al)	7429-90-5		0.4628	mg
Die Attach	2.852	mg	Supplier	Siloxanes and Silicones, di-Me, hydroxy- terminated, reaction products with Me hydrogen siloxanes and trimethoxy(3- (oxiranylmethoxy)propyl)silane	153890-18-7		0.5704	mg
			Supplier	1,1'-(Methylenedi-p- phenylene)bismaleimide	13676-54-5		1.2834	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.2852	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.2852	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.2852	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.1426	mg
Imaging Lens	29.239	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5388	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5388	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.1541	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5388	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5388	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5388	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.3907	mg
Lid Attach	1.459	mg	Supplier	2,2-Bis(glycidyloxyphenyl)propane polymer	25085-99-8		0.3647	mg
			Supplier	3,4-EPOXYCYCLOHEXYLMETHYL	2386-87-0		1.0578	mg
			Supplier	Misc.	Proprietary Data		0.0365	mg
Mold Compound	43.49	mg		Epoxy resin	proprietary data		10.7855	mg
-			Supplier	Other Additive Agents	Proprietary Data		1.3917	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.349	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.6591	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.3047	mg
Solder Ball	35.868	mg	Supplier	Silver (Ag)	7440-22-4		1.076	mg
			Supplier	Tin (Sn)	7440-31-5		34.6126	mg
			Supplier	Copper (Cu)	7440-50-8		0.1793	mg

Solder Mask	4.22	mg		Epoxy resin	proprietary data	0.5064	mg
			Supplier	Acrylate	Proprietary Data	1.612	mg
			Supplier	Talc	14807-96-6	0.1139	mg
			Supplier	Miscellaneous	Trade Secret	0.1561	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	1.8315	mg
Substrate Copper Foil	3.09	mg	Supplier	Copper (Cu)	7440-50-8	3.09	mg
Substrate - Core Material	16.24	mg		Epoxy resin	proprietary data	3.5192	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	12.7208	mg
Substrate Plating-Au	0.29	mg	Supplier	Gold (Au)	7440-57-5	0.29	mg
Substrate Plating-Cu	14.49	mg	Supplier	Copper (Cu)	7440-50-8	14.49	mg
Substrate Plating-Ni	0.67	mg	В	Nickel (Ni)	7440-02-0	0.67	mg
Wire Bond - Au	0.286	mg	Supplier	Gold (Au)	7440-57-5	0.286	mg